

JACK P. DICANIO (SBN 138782)
 Jack.DiCanio@skadden.com
 EMILY REITMEIER (SBN 305512)
 Emily.Reitmeier@skadden.com
 JERRY (JAE WOOK) LEE (SBN 333054)
 Jerry.Lee@skadden.com
 OSAMA ALKHAWAJA (SBN 334404)
 Osama.Alkhawaja@skadden.com
 SKADDEN, ARPS, SLATE, MEAGHER & FLOM LLP
 525 University Avenue
 Palo Alto, California 94301
 Telephone: (650) 470-4500
 Facsimile: (650) 470-4570

MATTHEW E. SLOAN (SBN 165165)
 Matthew.Sloan@skadden.com
 SKADDEN, ARPS, SLATE, MEAGHER & FLOM LLP
 300 South Grand Avenue, Suite 3400
 Los Angeles, California 90071-3144
 Telephone: (213) 687-5000
 Facsimile: (213) 687-5600

Attorneys for Defendant
 FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.

IN THE UNITED STATES DISTRICT COURT
FOR THE NORTHERN DISTRICT OF CALIFORNIA
SAN FRANCISCO DIVISION

UNITED STATES OF AMERICA,

 Plaintiff,

v.

UNITED MICROELECTRONICS
 CORPORATION, *et al.*,

Defendants.

CASE NO.: 3:18-cr-00465-MMC

**DEFENDANT FUJIAN JINHUA
 INTEGRATED CIRCUIT CO., LTD.'S
 EXHIBIT LIST**

Judge: The Honorable Maxine M. Chesney
 Trial Date: February 14, 2022

1 Pursuant to the April 15, 2021 Amended Scheduling Order in the above-captioned case (ECF
2 No. 160), Defendant Fujian Jinhua Integrated Circuit Co. Ltd. ("Jinhua") respectfully submits the
3 below list of exhibits it may introduce at trial in the above-captioned case. Jinhua will provide
4 translations of documents not in English prior to trial.

5 Jinhua reserves the right to supplement this list and to use additional documents, including
6 but not limited to for impeachment or cross-examination purposes, not identified here. In addition,
7 Jinhua reserves the right use at trial any exhibit listed by the government on its exhibit list (ECF No.
8 258) or any of the government's subsequent exhibit lists. Jinhua further reserves its right to object
9 to the admissibility of any exhibit, or part of any exhibit, or the purposes for which such exhibit is
10 being offered, notwithstanding that such exhibit is also identified herein. Jinhua further reserves the
11 right to supplement or amend this list, up to and during the trial of this matter.

12 DATED: January 11, 2022

13 SKADDEN, ARPS, SLATE, MEAGHER & FLOM LLP

14
15 By: /s/ Jack P. DiCanio
16 JACK P. DICANIO
17 *Attorneys for Defendant*
FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.

UNITED STATES DISTRICT COURT
NORTHERN DISTRICT OF CALIFORNIA

CASE NO. 3:18-cr-00465-MMC

DATE: January 11, 2022

UNITED STATES v. FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.

FUJIAN JINHUA'S EXHIBIT LIST

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3000			Coventor - Virtual Fab 14nm DRAM 2016.pdf	N/A
D3001			Coventor - Virtual Fab 14nm DRAM Mar 2016.pdf	N/A
D3002			Coventor AA Wiggle Simulation.pdf	N/A
D3003			Coventor DRAM Virtual Fab.pdf	N/A
D3004			Coventor-Technology.pdf	N/A
D3005			DRAM Process Simulation Tools - Coventor 2020.pdf	N/A
D3006			02/13/2017 15:05 Line Chats [Chinese]	D-0000160
D3007			Micron Technology, Inc. - Sanjay Mehrotra [Chinese]	D-0000800
D3008			Email - 11/29/2018 re: Publication of Information Security Regulations [Chinese]	JHICC-0000001
D3009			Email - 11/29/2018 re: Publication of Information Security Regulations [English]	JHICC-0000001T
D3010			Email Attachment re: Publication of Information Security Regulations [Chinese]	JHICC-0000002
D3011			Email Attachment re: Publication of Information Security Regulations [English]	JHICC-0000002T
D3012			Resignation Certificate	JHICC-0000005
D3013			03/09/2020 Employment Certificate - Feng Ming Kuo [Chinese]	JHICC-0000006
D3014			03/09/2020 Employment Certificate - Feng Ming Kuo [English]	JHICC-0000006T
D3015			Resignation Certificate Feng Ming Kuo	JHICC-0000007
D3016			Email - 01/28/2019 re: Aafile	JHICC-0000008
D3017			Email Attachment re: Aafile Presentation 20190128.pptx [Chinese]	JHICC-0000009
D3018			Email Attachment re: Aafile Presentation 20190128.pptx [English]	JHICC-0000009T
D3019			Consultant Hiring Contract [Chinese]	JHICC-0000012

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3020			Consultant Hiring Contract [English]	JHICC-0000012T
D3021			DD_DRAM Development Path in UMC_2018Jan25.pptx [Chinese]	JHICC-0000014
D3022			DD_DRAM Development Path in UMC_2018Jan25.pptx [English]	JHICC-0000014T
D3023			Patent - KR20060076348A [English]	N/A
D3024			Patent - KR20060076348A [Korean]	N/A
D3025			Patent - KR20160015783A [English]	N/A
D3026			Patent - KR20160015783A [Korean]	N/A
D3027			Elpida-Powerchip Patent License.pdf	MICRON00000011
D3028			process tla amendment.pdf	MICRON00000023
D3029			Project Night Sky - TTLA on 25nm DRAM Design Technology (Executed)_ (PALI.pdf	MICRON00000029
D3030			Project Night Sky - TTLA on 25nm DRAM Process Technology (Executed)PAL.pdf	MICRON00000054
D3031			25nm DRAM DESIGN TECHNOLOGY V90B D version Training time card	MICRON00000121
D3032			4G3D_DesignTrainingPlan_1126_27.xls	MICRON00000122
D3033			Document list A_plusPE.xlsx	MICRON00000123
D3034			Document list B_plusPE.xlsx	MICRON00000124
D3035			result.rtf	MICRON00000125
D3036			Timeline	MICRON00000841
D3037			Transitror%20dimention%20trend%20for%20DRAM%20development((Autosaved-	TAIWANHD-00000038
D3038			16702834.pptx	TAIWANHD-00000158
D3039			Microsoft_Excel_Worksheet1.xlsx	TAIWANHD-00000166
D3040			2E%20TEOS%20Roll%20off%20study((Unsaved-305741123726328848)).xls	TAIWANHD-00000250
D3041			DDR4 HCI TABLE.xlsx	TAIWANHD-00000355
D3042			F32_corner_20161017_V1.xlsx	TAIWANHD-00000421
D3043			UMC DRAM TCAD 20160919.pdf	TAIWANHD-00000467
D3044			DRAM_Process_Report-Sample(46nm chipwork report).pdf	TAIWANHD-00000674

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3045			DRAM S,H,M SA SWD 160317.pptx	TAIWANHD-00000691
D3046			TechInsights DRAM Roadmap-2015.pptx	TAIWANHD-00000699
D3047			TechInsights-DRAMRoadmap2014.ppt	TAIWANHD-00000701
D3048			F32 TV0 AJ88 mask information_20161223_v1.pptx	TAIWANHD-00001015
D3049			Project M - STI 卡通圖 V4 flow.pptx	TAIWANHD-00001025
D3050			Microsoft_PowerPoint____1.pptx	TAIWANHD-00001044
D3051			F32 STI~BWL FMEA Review-0715M.pptx	TAIWANHD-00001109
D3052			PM2 Device1 weekly update_201601018.pptx	TAIWANHD-00001610
D3053			F32 DRAM Power Line Condition.pptx	TAIWANHD-00002115
D3054			patent proposal 1.pptx	TAIWANHD-00002181
D3055			F32 WAT Program Testplan Check_20170124_SG.xlsx	TAIWANHD-00002236
D3056			F32 TV0_Device TEG Description_20161226.xlsx	TAIWANHD-00002250
D3057			F32_Device Weekly report_CM_20161226.pptx	TAIWANHD-00002299
D3058			F32 DRAM DEV Weekly Report (Liwei)_20170109.pptx	TAIWANHD-00002310
D3059			PM1 monthly report for JHICC_Nov_2016.pptx	TAIWANHD-00002601
D3060			F32 LV3 STRIP readiness 文甫 2016- 1227.xlsx	TAIWANHD-00003887
D3061			F32 FMEA Review 20170120.pptx	TAIWANHD-00004277
D3062			0000004.eml	TAIWANHD-00004607
D3063			F32 STI~BWL FMEA Review-0628.pptx	TAIWANHD-00016170
D3064			F32-6F2 Flow Chart-JS-20130910.ppt	TAIWANHD-00028161
D3065			(ALL) IMP conditions Table_20150318.xlsx	TAIWANHD-02125103
D3066			F32 Mini array and cell boundary.20160908.pptx	TAIWANHD-02161205
D3067			Schematic_1_checking_0104_V2.pptx	TAIWANHD-02161373
D3068			AJ88 到站預估-20170206-leading.xlsx	TAIWANHD-02161608
D3069			Project M Milestone_20151228.pptx	TAIWANHD-02161629

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3070			Cell CB CW 0420 B.pptx	TAIWANHD-02161663
D3071			DRAM RnD Technology Roadmap-20160808.pptx	TAIWANHD-02161668
D3072			DRAM工藝流程 and 技術藍圖report 20160811.pptx	TAIWANHD-02161671
D3073			0000070.eml	TAIWANHD-02165398
D3074			0000073.eml	TAIWANHD-02165401
D3075			0000081.eml	TAIWANHD-02165415
D3076			DRAM Reports 2010 - 2016.xlsx	TAIWANHD-02165416
D3077			0000100.eml	TAIWANHD-02165452
D3078			Mutual Non-disclosure Agreement.pdf	TAIWANHD-02165453
D3079			0000206.eml	TAIWANHD-02165589
D3080			F32 bWL OXIDE ETCH LV3 readiness.xlsx	TAIWANHD-02165947
D3081			F32_LML_20170113.xlsx	TAIWANHD-02166066
D3082			關於20171205 Micron Filed 的備註_0122.docx	UMCDOJ-00010951
D3083			PM1 monthly report_May_2018.pptx	UMCDOJ-00107083
D3084			1255.msg	UMCDOJ-00109607
D3085			1259.msg	UMCDOJ-00109611
D3086			1401.msg	UMCDOJ-00110001
D3087			DD_20180125-1.pptx	UMCDOJ-00110003
D3088			T5377s_T5833_T5833J Benchmark.pptx	UMCDOJ-00112549
D3089			2094.msg	UMCDOJ-00112797
D3090			PM1 monthly report_Nov_2017.pptx	UMCDOJ-00112798
D3091			image003.jpg	UMCDOJ-00113857
D3092			DRAM-UMC-2017-10-16-v1-lt_Xi-Wei.pdf	UMCDOJ-00113858
D3093			2371.msg	UMCDOJ-00114097
D3094			2386.msg	UMCDOJ-00114125

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3095			Tool Detail Config Summary.xlsx	UMCDOJ-00114589
D3096			招標書匯整.xlsx	UMCDOJ-00114590
D3097			2792.msg	UMCDOJ-00115499
D3098			UMC-DRAM_20170324_john_wang.pdf	UMCDOJ-00115502
D3099			3780.msg	UMCDOJ-00119418
D3100			Micron Analyst Conference 2017.pdf	UMCDOJ-00119419
D3101			0500.lnd	UMCDOJ-00125243
D3102			1032.lnd	UMCDOJ-00127069
D3103			Tool Demo Plan_07202016.pptx	UMCDOJ-00127071
D3104			3114.lnd	UMCDOJ-00132772
D3105			Project-M Progress Report_Mar 2017.pptx	UMCDOJ-00132774
D3106			1.xlsx	UMCDOJ-00132814
D3107			2.xls	UMCDOJ-00132815
D3108			Project-M Progress Report_Apr 2017.pptx	UMCDOJ-00133261
D3109			3337.lnd	UMCDOJ-00133758
D3110			DRAM Development Progress Report_APR_2017_V2簡.pptx	UMCDOJ-00133760
D3111			IT Buildup Strategy V2.5.pptx	UMCDOJ-00134246
D3112			1.xlsx	UMCDOJ-00134291
D3113			2.bmp	UMCDOJ-00134292
D3114			3.bmp	UMCDOJ-00134293
D3115			4.bmp	UMCDOJ-00134294
D3116			5.bmp	UMCDOJ-00134295
D3117			3469.lnd	UMCDOJ-00134478
D3118			CIS industry.docx	UMCDOJ-00134479
D3119			PM1 monthly report_May_2017_v1.pptx	UMCDOJ-00134548

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3120			3527.lnd	UMCDOJ-00134868
D3121			DRAM Development Progress Report_May_2017簡__V2.pptx	UMCDOJ-00134870
D3122			3530.lnd	UMCDOJ-00134951
D3123			Presentation 20170601 FJ.pptx	UMCDOJ-00134953
D3124			4293.lnd	UMCDOJ-00137696
D3125			F32s_TV1_MOU_20170815102011375.pdf	UMCDOJ-00137697
D3126			PM1 monthly report_Aug_2017.pptx	UMCDOJ-00137807
D3127			Tool Detail Config Summary.xlsx	UMCDOJ-00138611
D3128			4513.lnd	UMCDOJ-00138626
D3129			Request of Azimuthal Polarization 2017 0911_sf update.pptx	UMCDOJ-00138846
D3130			PM1 monthly report_Sep_2017.pptx	UMCDOJ-00139087
D3131			4644.lnd	UMCDOJ-00139222
D3132			4704.lnd	UMCDOJ-00139434
D3133			F32 Technology Transfer Proposal Rev2.pptx	UMCDOJ-00139436
D3134			4734.lnd	UMCDOJ-00139598
D3135			6F2 3x2 80x78 cell othogonal+Hexagonal layout.pptx	UMCDOJ-00139604
D3136			PM1 monthly report_Oct_2017.pptx	UMCDOJ-00140229
D3137			5066.lnd	UMCDOJ-00141394
D3138			5503.lnd	UMCDOJ-00143243
D3139			Annual report for JHICC_2017_part 1.pptx	UMCDOJ-00143525
D3140			Annual report for JHICC_2017_part 2.pptx	UMCDOJ-00143622
D3141			5883.lnd	UMCDOJ-00145064
D3142			JHICC Low Power DRAM Strategy-20180118.pptx	UMCDOJ-00145065
D3143			5979.lnd	UMCDOJ-00145454
D3144			F32 Technical Transfer 2018 0125pptx.pptx	UMCDOJ-00145455

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3145			PM1 monthly report_Feb_2018.pptx	UMCDOJ-00146564
D3146			PM2 weekly_20180302.pptx	UMCDOJ-00146725
D3147			6453.lnd	UMCDOJ-00147806
D3148			ICMAX Company profile_JHICC20180316.pdf	UMCDOJ-00147807
D3149			DDR3 Product Proposal_180409.pptx	UMCDOJ-00148096
D3150			20180410_Part number naming.pptx	UMCDOJ-00148545
D3151			PM1 monthly report_Apr_2018.pptx	UMCDOJ-00148975
D3152			PM1 monthly report_Jun_2018.pptx	UMCDOJ-00151503
D3153			20180614_Tera advantages .pdf	UMCDOJ-00151541
D3154			Tera Semicon Demo Proposal(20180619).pptx	UMCDOJ-00151549
D3155			PM1 monthly report_July_2018.pptx	UMCDOJ-00152776
D3156			PM2 Device1 F32s Device Target Ver0.1_20180726v1.pptx	UMCDOJ-00153137
D3157			PM1 monthly report_Aug_2018.pptx	UMCDOJ-00153775
D3158			PM1 monthly report_Sep_2018.pptx	UMCDOJ-00154508
D3159			DRAM工藝流程 and 技術藍圖report 20160811.pptx	UMCDOJ-00156047
D3160			2608.lnd	UMCDOJ-00156275
D3161			UMC Proposal.pdf	UMCDOJ-00156277
D3162			674.lnd	UMCDOJ-00159355
D3163			6F2 cell options_Project M-20160104.pptx	UMCDOJ-00159357
D3164			0896.lnd	UMCDOJ-00160034
D3165			6F2 3x2 80x78 cell othogonal+Hexagonal layout.pptx	UMCDOJ-00160060
D3166			3053.lnd	UMCDOJ-00172441
D3167			M Project impact.pptx	UMCDOJ-00172442
D3168			picture1.gif	UMCDOJ-00172446
D3169			3083.lnd	UMCDOJ-00172474

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3170			picture1.gif	UMCDOJ-00172476
D3171			Tool Demo Plan_07202016.pptx	UMCDOJ-00172570
D3172			3154.lnd	UMCDOJ-00172718
D3173			20160716 DRAMeXchange Presentation (晉江演講).pdf	UMCDOJ-00172720
D3174			3991.lnd	UMCDOJ-00175451
D3175			技術合同技術性收入核定表說明__20160907.pptx	UMCDOJ-00175493
D3176			DRAM Development for NCKU talk v1.pptx	UMCDOJ-00178345
D3177			F32 Alignment table.20160527.pptx	UMCDOJ-00180934
D3178			026.lnd	UMCDOJ-00186562
D3179			TechInsights-DRAM-Roadmap-2015.pdf	UMCDOJ-00186563
D3180			42.lnd	UMCDOJ-00187053
D3181			Schematic.pptx	UMCDOJ-00187054
D3182			6515.lnd	UMCDOJ-00191606
D3183			160613UMC DRAM Proposal(說明資料).pptx	UMCDOJ-00236242
D3184			F32 Process Training Material 20170904.pptx	UMCDOJ-00236627
D3185			201610_DRAM Roadmap & Micron 20nm DRAM.pdf	UMCDOJ-00237826
D3186			TechInsights DRAM Roadmap-2015.pptx	UMCDOJ-00237929
D3187			TechInsights-DRAMRoadmap2014.ppt	UMCDOJ-00237983
D3188			TechInsights in public computer for CMOS.pptx	UMCDOJ-00241327
D3189			F32 SC loop FMEA Review 20170322.pptx	UMCDOJ-00242671
D3190			SN Cs improvement 1206.pptx	UMCDOJ-00243953
D3191			STI APF HMO AMAT provide information.pdf	UMCDOJ-00244396
D3192			DRAM說明(聯電開發策略).pptx	UMCDOJ-00245399
D3193			STI gap-fill benchmarking.pptx	UMCDOJ-00245461
D3194			F32 DRAM Cell layout and Key Tech decision.pptx	UMCDOJ-00246222

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3195			2071.lnd	UMCDOJ-00268793
D3196			F32 DRAM Cell layout and Key Tech decision.pptx	UMCDOJ-00268794
D3197			2170.lnd	UMCDOJ-00269365
D3198			DRAM_Technology_Products_Roadmap- 2017.pdf	UMCDOJ-00269366
D3199			picture1.gif	UMCDOJ-00269374
D3200			0572.lnd	UMCDOJ-00275918
D3201			SNC recess recipe concept 演進.pptx	UMCDOJ-00275920
D3202			1689.lnd	UMCDOJ-00284532
D3203			BM2 2x node DRAM X-S image-SA, BL.ppt	UMCDOJ-00284533
D3204			6035.lnd	UMCDOJ-00294102
D3205			何建廷案大綱.docx	UMCDOJ-00294103
D3206			DRAM說明.pptx	UMCDOJ-00294107
D3207			6292.lnd	UMCDOJ-00296378
D3208			Samsung Memory_Business in 2013 Analyst Day.pdf	UMCDOJ-00296380
D3209			6711.lnd	UMCDOJ-00299558
D3210			picture1.gif	UMCDOJ-00299561
D3211			7225.lnd	UMCDOJ-00302956
D3212			T5377s_T5833_T5833J Benchmark.pptx	UMCDOJ-00302957
D3213			20171109_DRAM Product Mix Analysis_Update.pptx	UMCDOJ-00302958
D3214			5986.lnd	UMCDOJ-00313401
D3215			F32 AM01 SC-BC Short Penetration 091118.pptx	UMCDOJ-00313404
D3216			picture1.gif	UMCDOJ-00313411
D3217			picture2.gif	UMCDOJ-00313412
D3218			6879.lnd	UMCDOJ-00317320
D3219			160613UMC DRAM Proposal(說明資料).pptx	UMCDOJ-00317322

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3220			153.lnd	UMCDOJ-00320140
D3221			picture1.gif	UMCDOJ-00320141
D3222			picture2.gif	UMCDOJ-00320142
D3223			3894.lnd	UMCDOJ-00365603
D3224			UMC R&D Capability for DRAM Process Development.pptx	UMCDOJ-00365605
D3225			664.lnd	UMCDOJ-00373302
D3226			Project M Process Flow @ 0517 2016.pptx	UMCDOJ-00373303
D3227			057.lnd	UMCDOJ-00395774
D3228			picture1.gif	UMCDOJ-00395776
D3229			picture2.gif	UMCDOJ-00395777
D3230			5588.lnd	UMCDOJ-00399085
D3231			picture1.gif	UMCDOJ-00399086
D3232			6022.lnd	UMCDOJ-00399227
D3233			G-RTP-DRAM32N-1P3M-TLR-Ver0_1P2- 20160725.doc	UMCDOJ-00399232
D3234			188.lnd	UMCDOJ-00420230
D3235			s-company 20nm 4Gb DDR4_001.jpg	UMCDOJ-00420241
D3236			s-company 20nm 4Gb DDR4.jpg	UMCDOJ-00420242
D3237			h-company 21nm 4Gb DDR4.jpg	UMCDOJ-00420243
D3238			PFA Request for BM SA structure_V3.pptx	UMCDOJ-00420244
D3239			PFA Request for BM SA structure_V2.pptx	UMCDOJ-00420253
D3240			PFA Request for BM SA structure_V1.pptx	UMCDOJ-00420260
D3241			AJ55 to AJ88 evolution_3_vs AJ88 (etch feedback).xlsx	UMCDOJ-00442222
D3242			2017 NBD 方針展開_PM1ET_Q4_2017.xlsx	UMCDOJ-00442782
D3243			PM1_2018 方針展開_ 工作表 v1 (ET).xlsx	UMCDOJ-00443469
D3244			Technical Transfer - Polyimide.pptx	UMCDOJ-00447766

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3245			MMHKELLISO-B01 config.pptx	UMCDOJ-00447852
D3246			PM1 monthly report_July_2017 (ET).pptx	UMCDOJ-00448730
D3247			F32S Monthly Report (Etch) 0926.pptx	UMCDOJ-00475722
D3248			DRAM BEOL etch process introduction v220160802.pptx	UMCDOJ-00484236
D3249			1.xlsx	UMCDOJ-00484261
D3250			2.xlsx	UMCDOJ-00484262
D3251			PM1-Etch Monthly Report 20161114.pptx	UMCDOJ-00487409
D3252			Schematic_1_checking_0104_V2 for bl Side wall SiN estimation 2016.pptx	UMCDOJ-00488768
D3253			DRAM Development Progress_0815_v4_簡 .pptx	UMCDOJ-00489146
D3254			Project M_Milestone_20160316_sf tzou.pptx	UMCDOJ-00489225
D3255			PM1 monthly report for JHICC_Feb_2017.pptx	UMCDOJ-00489423
D3256			PM1 monthly report for JHICC_Mar_2017.pptx	UMCDOJ-00489447
D3257			PM1 monthly report_Jan_2018.pptx	UMCDOJ-00489469
D3258			1.xlsx	UMCDOJ-00489496
D3259			Project M_Module Weekly Report_20160712.pptx	UMCDOJ-00489683
D3260			PM1 monthly report_Jun_2017.pptx	UMCDOJ-00489979
D3261			PM1 monthly report_Nov_2017.pptx	UMCDOJ-00490007
D3262			028.lnd	UMCDOJ-00492178
D3263			6F2 cell options_Project M-20160114_SF update-rev2.pptx	UMCDOJ-00492179
D3264			030.lnd	UMCDOJ-00492204
D3265			Project M Milestone V2_20160118-neillee.pptx	UMCDOJ-00492207
D3266			1.xlsx	UMCDOJ-00492219
D3267			26.lnd	UMCDOJ-00493517
D3268			Samsung 20 sample.pdf	UMCDOJ-00493520
D3269			32.lnd	UMCDOJ-00493581

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3270			6F2 cell options_Project M-20160104.pptx	UMCDOJ-00493583
D3271			F32 3x2.xlsx	UMCDOJ-00493587
D3272			picture1.gif	UMCDOJ-00493588
D3273			7328.msg	UMCDOJ-00674195
D3274			MMPOLY-B02 TierII ER Report_Customer.pptx	UMCDOJ-00674198
D3275			Project M master plan_v1.xlsx	UMCDOJ-00680385
D3276			576.lnd	UMCDOJ-00682084
D3277			DPT comparison.pptx	UMCDOJ-00682087
D3278			Project-M Progress Report_20170309_v3.pptx	UMCDOJ-00705010
D3279			0793.lnd	UMCDOJ-00710228
D3280			PM1 Weekly Report_sftzou_20170405.pptx	UMCDOJ-00710230
D3281			PM1 monthly report for JHICC_Feb_2017.pptx	UMCDOJ-00711903
D3282			picture1.gif	UMCDOJ-00711927
D3283			picture2.gif	UMCDOJ-00711928
D3284			PRS -- L45 SP1-20071102.xls	UMCDOJ-00721680
D3285			Project-M Progress Report_201710_v1_sfupdate.pptx	UMCDOJ-00739427
D3286			PM1 monthly report_Sep_2017.pptx	UMCDOJ-00740302
D3287			2669.lnd	UMCDOJ-00776596
D3288			JHICC SupremaXP HDIS process tuning update and proposal_011818.pdf	UMCDOJ-00776597
D3289			2723.lnd	UMCDOJ-00777022
D3290			SNC recess recipe concept 演進.pptx	UMCDOJ-00777024
D3291			K65KC.46#07_C_-0001.jpg	UMCDOJ-00777026
D3292			K65KC.46#07_C_-0002.jpg	UMCDOJ-00777027
D3293			K65KC.46#07_C_-0003.jpg	UMCDOJ-00777028
D3294			K65KC.46#07_C_-0004.jpg	UMCDOJ-00777029

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3295			K65KC.46#07_C_-0005.jpg	UMCDOJ-00777030
D3296			K65KC.46#07_C_-0006.jpg	UMCDOJ-00777031
D3297			K65KC.46#07_E_-0001.jpg	UMCDOJ-00777032
D3298			K65KC.46#07_E_-0002.jpg	UMCDOJ-00777033
D3299			K65KC.46#07_E_-0003.jpg	UMCDOJ-00777034
D3300			K65KC.46#07_E_-0004.jpg	UMCDOJ-00777035
D3301			K65KC.46#07_E_-0005.jpg	UMCDOJ-00777036
D3302			K65KC.46#07_E_-0006.jpg	UMCDOJ-00777037
D3303			Project-M Progress Report_201706_v3.pptx	UMCDOJ-00826286
D3304			Project-M Progress Report_201706_v2.pptx	UMCDOJ-00826313
D3305			PM1 monthly report_Oct_2018.pptx	UMCDOJ-00833262
D3306			233.lnd	UMCDOJ-00838452
D3307			Project M mini array_version 3.2 - 20160325.pptx	UMCDOJ-00838455
D3308			Project M mini array_version 3.1 - 20160323.pptx	UMCDOJ-00838465
D3309			1153.lnd	UMCDOJ-00841489
D3310			Peripheral Plane View_SEM.pptx	UMCDOJ-00841492
D3311			Project M mini array_version 2.2 - 20160309_SR_modified.pptx	UMCDOJ-00841520
D3312			1532.lnd	UMCDOJ-00847051
D3313			Project-M Progress Report_May 2017.pptx	UMCDOJ-00847052
D3314			1781.lnd	UMCDOJ-00882811
D3315			Reverse Engineering for SNPAD W residue.pptx	UMCDOJ-00882815
D3316			D1-YS Gate_88k-3.jpg	UMCDOJ-00882816
D3317			D1-YS Gate_88k-2.jpg	UMCDOJ-00882817
D3318			D1-YS Gate_88k-1.jpg	UMCDOJ-00882818
D3319			D1-YS Gate_64k-2.jpg	UMCDOJ-00882819

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3320			D1-YS Gate_64k.jpg	UMCDOJ-00882820
D3321			D1-YS Gate_39k.jpg	UMCDOJ-00882821
D3322			D1-YS Gate_26.5k.jpg	UMCDOJ-00882822
D3323			D1-YS Gate_13.5k.jpg	UMCDOJ-00882823
D3324			D1-YS Gate_6.3k.jpg	UMCDOJ-00882824
D3325			D1_320k-1.jpg	UMCDOJ-00882825
D3326			D1_320k.jpg	UMCDOJ-00882826
D3327			D1_160k.jpg	UMCDOJ-00882827
D3328			D1_79k.jpg	UMCDOJ-00882828
D3329			D1_630k.jpg	UMCDOJ-00882829
D3330			D1_320k-2.jpg	UMCDOJ-00882830
D3331			D3-SAP_13.5k.jpg	UMCDOJ-00882831
D3332			D3-SAP_8.9k.jpg	UMCDOJ-00882832
D3333			D3-SAP_6.3k.jpg	UMCDOJ-00882833
D3334			D3-Cell_88k.jpg	UMCDOJ-00882834
D3335			D3-Cell_64k.jpg	UMCDOJ-00882835
D3336			D3-Cell_39k.jpg	UMCDOJ-00882836
D3337			D3-Cell_26.5k.jpg	UMCDOJ-00882837
D3338			D3-Cell_13.5k.jpg	UMCDOJ-00882838
D3339			D3-SAP_88k-1.jpg	UMCDOJ-00882839
D3340			D3-SAP_88k.jpg	UMCDOJ-00882840
D3341			D3-SAP_64k.jpg	UMCDOJ-00882841
D3342			D3-SAP_39k.jpg	UMCDOJ-00882842
D3343			D3-SAP_26.5k.jpg	UMCDOJ-00882843
D3344			D3_320k.jpg	UMCDOJ-00882844

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3345			D3_160k.jpg	UMCDOJ-00882845
D3346			D3_79k.jpg	UMCDOJ-00882846
D3347			D3_320k-1.jpg	UMCDOJ-00882847
D3348			picture1.gif	UMCDOJ-00882848
D3349			picture2.gif	UMCDOJ-00882849
D3350			picture3.gif	UMCDOJ-00882850
D3351			picture4.gif	UMCDOJ-00882851
D3352			picture5.gif	UMCDOJ-00882852
D3353			1783.lnd	UMCDOJ-00894540
D3354			3707.lnd	UMCDOJ-00904117
D3355			TP BM.xlsx	UMCDOJ-00904119
D3356			picture1.gif	UMCDOJ-00904120
D3357			picture2.gif	UMCDOJ-00904121
D3358			picture3.gif	UMCDOJ-00904122
D3359			picture4.gif	UMCDOJ-00904123
D3360			RE report-Micron-201808021.ppt	UMCDOJ-00916015
D3361			RE report-UMC-20180821.ppt	UMCDOJ-00916081
D3362			161.lnd	UMCDOJ-00919364
D3363			F32 technology development 20181023.pptx	UMCDOJ-00919365
D3364			1140.lnd	UMCDOJ-00922326
D3365			动态随机存储器研发月报 (2016.11).pdf	UMCDOJ-00922327
D3366			Gross Die Estimation_Rev0.0.pdf	UMCDOJ-00923164
D3367			2958.lnd	UMCDOJ-00926174
D3368			20170117 Development plan for JSC meeting.pptx	UMCDOJ-00926175
D3369			3111.lnd	UMCDOJ-00926601

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3370			F32 Technology Transfer Proposal.pptx	UMCDOJ-00926602
D3371			004.lnd	UMCDOJ-00928448
D3372			6F2 cell options_Project M-20160104_2.pptx	UMCDOJ-00928458
D3373			picture1.gif	UMCDOJ-00928465
D3374			picture2.gif	UMCDOJ-00928466
D3375			26.lnd	UMCDOJ-00929145
D3376			Samsung 20 sample.pdf	UMCDOJ-00929148
D3377			BEOL process discussion-ver2.pptx	UMCDOJ-01035898
D3378			0169.lnd	UMCDOJ-01036672
D3379			design rule 0.1P5~0.1P6 value_v1.xlsx	UMCDOJ-01036676
D3380			picture2.gif	UMCDOJ-01036678
D3381			0187.lnd	UMCDOJ-01036708
D3382			design rule 0.1P5~0.1P6 value_v2.xlsx	UMCDOJ-01036713
D3383			picture2.gif	UMCDOJ-01036715
D3384			Design Cooperation Comparison.pptx	UMCDOJ-01040964
D3385			0751.lnd	UMCDOJ-01041447
D3386			2680.lnd	UMCDOJ-01047135
D3387			Training Session- 01 DDR Evolution and DRAM Technology Roadmap.pptx	UMCDOJ-01047136
D3388			Training Session- 02 DRAM Layout and Voltage Terms.pptx	UMCDOJ-01047160
D3389			2886.lnd	UMCDOJ-01047911
D3390			DRAM storage capacitor pattern and process design 0703.pptx	UMCDOJ-01047913
D3391			TextScan.Htm	UMCDOJ-01047972
D3392			2911.lnd	UMCDOJ-01048055
D3393			picture1.gif	UMCDOJ-01048115
D3394			3138.lnd	UMCDOJ-01048976

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3395			TLR revision 紀錄_20180711_v6.xlsx	UMCDOJ-01048977
D3396			picture1.gif	UMCDOJ-01048978
D3397			00499.msg	UMCDOJ-01058147
D3398			RE report-Micron-智發20180914.pptx	UMCDOJ-01058148
D3399			DRAM 元件與製程分析報告r3-P1-P9.pptx	UMCDOJ-01058317
D3400			DRAM 元件與製程分析報告r3-P17-P21.pptx	UMCDOJ-01058326
D3401			00506.msg	UMCDOJ-01058347
D3402			DRAM 元件與製程分析報告r3-P1-P9.pptx	UMCDOJ-01058352
D3403			00561.msg	UMCDOJ-01058738
D3404			00563.msg	UMCDOJ-01058743
D3405			未命名的附件 01207.gif	UMCDOJ-01058746
D3406			00566.msg	UMCDOJ-01058786
D3407			00579.msg	UMCDOJ-01058823
D3408			00804.msg	UMCDOJ-01060217
D3409			RE report-Micron-201808010.ppt	UMCDOJ-01060218
D3410			00905.msg	UMCDOJ-01060644
D3411			00913.msg	UMCDOJ-01060668
D3412			RE report-Micron-20180727.ppt	UMCDOJ-01060669
D3413			00978.msg	UMCDOJ-01060902
D3414			未命名的附件 02316.gif	UMCDOJ-01060903
D3415			Micron-Active-explain.pptx	UMCDOJ-01060904
D3416			00999.msg	UMCDOJ-01060962
D3417			SIPTK Quotation 20180720-UMC.pdf	UMCDOJ-01060963
D3418			01032.msg	UMCDOJ-01061053
D3419			F32 Technical Transfer Plan 20170728.pptx	UMCDOJ-01069436

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3420			1.xls	UMCDOJ-01069441
D3421			04850.msg	UMCDOJ-01071442
D3422			Everspin_Response_and_Questions_June2017. pdf	UMCDOJ-01071446
D3423			09958.msg	UMCDOJ-01080304
D3424			11929.msg	UMCDOJ-01086415
D3425			TC_0114-35632-O-5DC-100.pdf	UMCDOJ-01086416
D3426			TC_0314-36479-O-5DM-100.pdf	UMCDOJ-01086423
D3427			5503.lnd	UMCDOJ-01094640
D3428			5620.lnd	UMCDOJ-01094688
D3429			5881.lnd	UMCDOJ-01094760
D3430			關於20171205 Micron Filed 的備註 _0117.docx	UMCDOJ-01094761
D3431			071.lnd	UMCDOJ-01114748
D3432			picture1.gif	UMCDOJ-01114753
D3433			picture2.gif	UMCDOJ-01114754
D3434			picture3.gif	UMCDOJ-01114755
D3435			072.lnd	UMCDOJ-01114756
D3436			picture1.gif	UMCDOJ-01114762
D3437			picture2.gif	UMCDOJ-01114763
D3438			picture3.gif	UMCDOJ-01114764
D3439			1058.lnd	UMCDOJ-01129011
D3440			BM2 2x node DRAM P-V image.ppt	UMCDOJ-01129014
D3441			1179.lnd	UMCDOJ-01129333
D3442			1527.lnd	UMCDOJ-01131705
D3443			2197.lnd	UMCDOJ-01136057
D3444			JD_cell device.doc	UMCDOJ-01136059

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3445			1938.lnd	UMCDOJ-01138860
D3446			3905.lnd	UMCDOJ-01142371
D3447			UMC Proposal.pdf	UMCDOJ-01142375
D3448			computing_DDR4_H5AN4G4(8_6)NAFR(Rev 1.0)_hynix.pdf	UMCDOJ-01142436
D3449			0643.lnd	UMCDOJ-01143575
D3450			INVOICE.pdf	UMCDOJ-01143577
D3451			1007.lnd	UMCDOJ-01144329
D3452			201610_UMC Q&A.pptx	UMCDOJ-01144330
D3453			4184.lnd	UMCDOJ-01150686
D3454			4187.lnd	UMCDOJ-01150691
D3455			1080.lnd	UMCDOJ-01155059
D3456			1154.lnd	UMCDOJ-01155381
D3457			DRAM Development Path in UMC_v1.pptx	UMCDOJ-01155382
D3458			1283.lnd	UMCDOJ-01155923
D3459			UMC035670 - F.xlsx	UMCDOJ-01155931
D3460			picture1.gif	UMCDOJ-01155932
D3461			4092.lnd	UMCDOJ-01170754
D3462			UMC design rule for F32-SA production.xlsx	UMCDOJ-01170755
D3463			5062.lnd	UMCDOJ-01172929
D3464			F32 6F2(3x2,2x3) discussion- JT_20160510_rev4.pptx	UMCDOJ-01172930
D3465			4180.lnd	UMCDOJ-01173589
D3466			design rule 0.1P5~0.1P6 value_v6 by ltj(modified)_v4.xlsx	UMCDOJ-01173592
D3467			Supporting data(others info.).pptx	UMCDOJ-01173593
D3468			F32 DRC analysis_20170105_v1.pptx	UMCDOJ-01173676
D3469			design rule 0.1P5~0.1P6 value_v6 by ltj(modified)_v2.xlsx	UMCDOJ-01173713

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3470			Supporting data of UMI 20160314ver..pptx	UMCDOJ-01173714
D3471			20160711 ESMT meeting minutes.xlsx	UMCDOJ-01173758
D3472			design rule 0.1P5~0.1P6 value_v6 by ltj(modified)_v1.xlsx	UMCDOJ-01173759
D3473			design rule 0.1P5~0.1P6 value_v6 by ltj(modified).xlsx	UMCDOJ-01173760
D3474			design rule 0.1P5~0.1P6 value_v6 by ltj.xlsx	UMCDOJ-01173761
D3475			4217.lnd	UMCDOJ-01173947
D3476			Presentation 20171003 MoEA.pptx	UMCDOJ-01173948
D3477			DRAM chip top view.pptx	UMCDOJ-01174949
D3478			美光案資料準備_20171018.pptx	UMCDOJ-01175558
D3479			4947.lnd	UMCDOJ-01175780
D3480			r_8b_drm_25_f_99_07_0.pdf	UMCDOJ-01175783
D3481			r_8c_drm_21_f_99_10_0.pdf	UMCDOJ-01175804
D3482			picture1.gif	UMCDOJ-01175828
D3483			picture2.gif	UMCDOJ-01175829
D3484			5012.lnd	UMCDOJ-01176084
D3485			R_8F_DRM_18_D_01_05_0.pdf	UMCDOJ-01176088
D3486			R_CA_DRM_15_D_02_08_GRC_S.pdf	UMCDOJ-01176099
D3487			picture1.gif	UMCDOJ-01176114
D3488			picture2.gif	UMCDOJ-01176115
D3489			4829.lnd	UMCDOJ-01178229
D3490			4895.lnd	UMCDOJ-01182549
D3491			技術移轉清單V0.1-20171206V0.5.xlsx	UMCDOJ-01182551
D3492			5243.lnd	UMCDOJ-01183177
D3493			G-03-DRAM15-2.8V_3.3V-5P2M-TLR-Ver.0.3 obsoleted_P1.pdf	UMCDOJ-01183178
D3494			4653.lnd	UMCDOJ-01184721

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3495			UMC F32 DRAM to JHICC Transfer Document List.xlsx	UMCDOJ-01184723
D3496			2393.lnd	UMCDOJ-01188743
D3497			D3 screen.xlsx	UMCDOJ-01188749
D3498			2480.lnd	UMCDOJ-01188840
D3499			UMC DRAM development concept –Storage Node 0718.pptx	UMCDOJ-01188841
D3500			2548.lnd	UMCDOJ-01188920
D3501			UMC F32 DRAM to JHICC Transfer Document List-v3.xlsx	UMCDOJ-01188921
D3502			2553.lnd	UMCDOJ-01188925
D3503			技術文件清單V0.1-20180718-version1.xlsx	UMCDOJ-01188926
D3504			2725.lnd	UMCDOJ-01189578
D3505			SIPTK Quotation 20180720-UMC.pdf	UMCDOJ-01189579
D3506			3719.lnd	UMCDOJ-01189593
D3507			2814.lnd	UMCDOJ-01189658
D3508			技術文件清單V0.1-20180718-version2.xlsx	UMCDOJ-01189660
D3509			4009.lnd	UMCDOJ-01190201
D3510			PM2 Device1 F32s Device Target Ver0.1_20180726v1.pptx	UMCDOJ-01190203
D3511			3087.lnd	UMCDOJ-01190312
D3512			UMC DRAM development concept –Buried Wordline 0727.pptx	UMCDOJ-01190313
D3513			3115.lnd	UMCDOJ-01190339
D3514			RE report-UMC-20180727.ppt	UMCDOJ-01190341
D3515			3116.lnd	UMCDOJ-01190380
D3516			RE report-Micron-20180727.ppt	UMCDOJ-01190381
D3517			3509.lnd	UMCDOJ-01191125
D3518			RE report-Micron-201808010.ppt	UMCDOJ-01191126
D3519			3745.lnd	UMCDOJ-01191883

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3520			RE report-UMC-20180821.ppt	UMCDOJ-01191884
D3521			1431.lnd	UMCDOJ-01193141
D3522			DRAM 元件與製程分析報告-P1-P12.pptx	UMCDOJ-01193142
D3523			DRAM 元件與製程分析報告P13-19.pptx	UMCDOJ-01193155
D3524			2275.lnd	UMCDOJ-01194849
D3525			F32 SA SWD eFuse for SA1 181011.pptx	UMCDOJ-01194876
D3526			DDR3 reverse engineering analysis_20181009.pptx	UMCDOJ-01194889
D3527			2603.lnd	UMCDOJ-01195513
D3528			F32 technology development 20181023.pptx	UMCDOJ-01195514
D3529			3683.lnd	UMCDOJ-01197070
D3530			A New Layout Design to Generate Variable Active Edge Shape in DRAM	UMCDOJ-01197071
D3531			9679901 idea source.pptx	UMCDOJ-01197098
D3532			3057.lnd	UMCDOJ-01197483
D3533			Comparison.xlsx	UMCDOJ-01197484
D3534			3113.lnd	UMCDOJ-01197536
D3535			Comparison-1.xlsx	UMCDOJ-01197538
D3536			3298.lnd	UMCDOJ-01197743
D3537			SC Development 1211.pptx	UMCDOJ-01197745
D3538			3430.lnd	UMCDOJ-01198031
D3539			F32 process BKM ---STI---v5.pptx	UMCDOJ-01198032
D3540			043.lnd	UMCDOJ-01198549
D3541			081.lnd	UMCDOJ-01198556
D3542			TechInsights-DRAM-Roadmap-2015.pdf	UMCDOJ-01198557
D3543			294.lnd	UMCDOJ-01199503
D3544			Applied Materials APTD Lab and Capabilities (May'16).pdf	UMCDOJ-01199505

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3545			0346.lnd	UMCDOJ-01200292
D3546			TV0 Testing update for UMI monthly meeting- 20170213.pdf	UMCDOJ-01200299
D3547			312.lnd	UMCDOJ-01200689
D3548			1. JSC Proposed SWD.pdf	UMCDOJ-01200696
D3549			2. F32s 8Gb LP4 Gross Die and Overhead Break Down_Rev1.0.pdf	UMCDOJ-01200703
D3550			1. F32s 8Gb LP4 Gross Die and Overhead Break Down.pdf	UMCDOJ-01200707
D3551			740.lnd	UMCDOJ-01200794
D3552			761.lnd	UMCDOJ-01200833
D3553			picture1.gif	UMCDOJ-01200837
D3554			773.lnd	UMCDOJ-01200847
D3555			picture1.gif	UMCDOJ-01200852
D3556			786.lnd	UMCDOJ-01200861
D3557			picture2.gif	UMCDOJ-01200868
D3558			791.lnd	UMCDOJ-01200882
D3559			0.3E88.gif;x-apple-part-url	UMCDOJ-01200890
D3560			795.lnd	UMCDOJ-01200891
D3561			picture1.gif	UMCDOJ-01200892
D3562			803.lnd	UMCDOJ-01200893
D3563			1015.lnd	UMCDOJ-01201059
D3564			MAT cell array_edge cell_corner cell_20160229.pptx	UMCDOJ-01201060
D3565			1018.lnd	UMCDOJ-01201071
D3566			7163.lnd	UMCDOJ-01201544
D3567			J_candiate_list.xlsx	UMCDOJ-01201548
D3568			Inpartners Profile(Head Hunting) .pptx	UMCDOJ-01201549
D3569			7856.lnd	UMCDOJ-01201606

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3570			Xperi - UMC 14 March Meeting.pdf	UMCDOJ-01201611
D3571			5233.lnd	UMCDOJ-01414023
D3572			Preliminary images Exynos 7420.pdf	UMCDOJ-01414027
D3573			Chronology 20181022-V2.pptx	UMCDOJ-01680260
D3574			TLR revision 紀錄_20171123_v3.xlsx	UMCDOJ-01760852
D3575			2345.lnd	UMCDOJ-01761364
D3576			34條TLR-supporting data.pptx	UMCDOJ-01761365
D3577			34條TLR資料對應表.xlsx	UMCDOJ-01761431
D3578			複本 0.1P3 討論結果與改版原因 _20171115.xlsx	UMCDOJ-01761432
D3579			5445.lnd	UMCDOJ-01821710
D3580			UMC design rule 改版紀錄_0.1P2~0.1P3.ppt	UMCDOJ-01821711
D3581			聯電F32 design rule 改版紀錄 0.1P2~0.1P3.xlsx	UMCDOJ-01821718
D3582			3032.lnd	UMCDOJ-01827233
D3583			F32-SA design rule comparison_20170630.xlsx	UMCDOJ-01827237
D3584			F32-SA design rule comparison_20170628.xlsx	UMCDOJ-01827238
D3585			GT-RPT-170411-002_Ver.0.2(Cover Page).pdf	UMCDOJ-01827239
D3586			PM2 weekly_20180622.pptx	UMCDOJ-01863581
D3587			4812.lnd	UMCDOJ-02657949
D3588			PPID Naming Rule.pptx	UMCDOJ-02657950
D3589			picture1.gif	UMCDOJ-02657963
D3590			0937.lnd	UMCDOJ-02800661
D3591			picture1.gif	UMCDOJ-02800664
D3592			201610_DRAM Roadmap & Micron 20nm DRAM.pdf	UMCDOJ-02844696
D3593			3554.lnd	UMCDOJ-02895005
D3594			Project-M Progress Report_201707_v3.pptx	UMCDOJ-02895006

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3595			工業局_20151127.pptx	UMCDOJ-02967310
D3596			010a-美光与联电洽谈经过.docx	UMCDOJ-02967662
D3597			073440.msg	UMCDOJ-03126236
D3598			海峡两岸存储器建设项目专家论证会议议程10.18.doc	UMCDOJ-03126237
D3599			海峡两岸存储器生产线建设项目可行性评估报告-18日版.docx	UMCDOJ-03126238
D3600			015a-证人于恆祥证言.docx	UMCDOJ-03163941
D3601			Flow STI~TP.pptx	UMCDOJ-03205745
D3602			F32 TV0 Flow FMEA Review (SN)20160730.pptx	UMCDOJ-03206980
D3603			InterCap model discussion_0603.pptx	UMCDOJ-03210891
D3604			DRAM S,H,M SA SWD 160317.pptx	UMCDOJ-03241860
D3605			2217.lnd	UMCDOJ-03328942
D3606			Project M weekly meeting material 20170518_1.pptx	UMCDOJ-03328943
D3607			160613UMC DRAM Proposal(説明資料).pptx	UMCDOJ-03407820
D3608			TechInsights-DRAM-ROADMAP-052013-LONG-version.pdf	UMCDOJ-03502587
D3609			BC.pptx	UMCDOJ-03619141
D3610			DRAM Development Progress Report_APR_2017_V3簡.pptx	UMCDOJ-03619742
D3611			DRAM Development Progress Report_May_2017簡.pptx	UMCDOJ-03619897
D3612			PM1 monthly report for JHICC_Jan_2017.pptx	UMCDOJ-03620923
D3613			PM1 monthly report_Apr_2017.pptx	UMCDOJ-03623553
D3614			Check.pptx	UMCDOJ-03624886
D3615			1.xlsx	UMCDOJ-03625009
D3616			DRAM Development Path in UMC_20180120.pptx	UMCDOJ-03625240
D3617			DRAM Development Progress Report_Jun_2017簡.pptx	UMCDOJ-03626396
D3618			DRAM PM1研發進度 UMC_201807_40min_v3_簡.pptx	UMCDOJ-03627557
D3619			1.xlsx	UMCDOJ-03627678

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3620			DRAM Development Path in UMC_v2.pptx	UMCDOJ-03679912
D3621			Process Flow Roadmap_August 2017.pdf	UMCDOJ-03680702
D3622			016a-证人鄒世芳证言(Final).docx	UMCDOJ-03680981
D3623			AJ55 to AJ88 evolution.xlsx	UMCDOJ-03681028
D3624			CONFIDENTIAL UMC Analysis by Experts 09012018.pptx	UMCDOJ-03681034
D3625			DRAM Project Q&A_20171127.pptx	UMCDOJ-03681175
D3626			UMI_華_meeting_20160511.pdf	UMCDOJ-03828714
D3627			UMI_華Pj Monthly Mtg_20160615.pdf	UMCDOJ-03828740
D3628			UMI_華Pj Monthly Mtg_20160713.pdf	UMCDOJ-03828755
D3629			UMI_華Pj Monthly Mtg_20160809.pdf	UMCDOJ-03828778
D3630			UMI_華Pj Monthly Mtg_20160906.pdf	UMCDOJ-03828804
D3631			UMI_華Pj Monthly Mtg_20161011.pdf	UMCDOJ-03828809
D3632			UMI_華Pj Monthly Mtg_20161108.pdf	UMCDOJ-03828829
D3633			UMI_華Pj Monthly Mtg_20170111.pdf	UMCDOJ-03828848
D3634			UMI_華Pj Monthly Mtg_20170214.pdf	UMCDOJ-03828863
D3635			UMI_華Pj_evalDRC_Sum_Detail_161011.pdf	UMCDOJ-03828872
D3636			華Pj Design Review_20161206.pdf	UMCDOJ-03828932
D3637			華Pj Monthly Mtg May 11th AI result.pdf	UMCDOJ-03829003
D3638			DRAM Development Path in UMC_for Board Member.pptx	UMCDOJ-03859402
D3639			BM Pitch discussion.xlsx	UMCDOJ-03859442
D3640			2.pdf	UMCDOJ-03866561
D3641			UMC Tool key component review.xls	UMCDOJ-03866569
D3642			DRAM Development Progress Report_May_ 2017簡.pptx	UMCDOJ-03866600
D3643			Presentation 20170601 FJ.pptx	UMCDOJ-03871296
D3644			PM1 monthly report_May Patent Filing.pptx	UMCDOJ-03872983

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3645			JHICC2018 budget input output plan for 3 years rolling1216-20K.XLSX	UMCDOJ-03874472
D3646			PM1 monthly report_Mar_2017.pptx	UMCDOJ-03937262
D3647			DRAM Development Progress Report_APR_2017.pptx	UMCDOJ-03938788
D3648			PM1 monthly report_Sep_2017.pptx	UMCDOJ-03953755
D3649			2971.lnd	UMCDOJ-04085606
D3650			20160225 NGR DRAM Application.pdf	UMCDOJ-04085608
D3651			UMC step naming.xlsx	UMCDOJ-04088956
D3652			DRAM Development Progress_0519.pptx	UMCDOJ-04103350
D3653			6138.lnd	UMCDOJ-04109817
D3654			Etch Bi-weekly report 20160719.pptx	UMCDOJ-04109819
D3655			picture1.gif	UMCDOJ-04109827
D3656			picture5.gif	UMCDOJ-04204308
D3657			picture6.gif	UMCDOJ-04204309
D3658			DRAM Development Progress_0815_v2.pptx	UMCDOJ-04208283
D3659			UMC step naming.xlsx	UMCDOJ-04362023
D3660			1166.lnd	UMCDOJ-04368944
D3661			Pitch size summary.xlsx	UMCDOJ-04368946
D3662			picture1.gif	UMCDOJ-04368947
D3663			PM1 monthly report_April Patent Filing.pptx	UMCDOJ-04373158
D3664			picture1.gif	UMCDOJ-04373161
D3665			one page summary of litho 2017 0417 --- JHICC.pptx	UMCDOJ-04373181
D3666			AJ88 LITHO Pilot Summary 2017 0417 for JHICC.xlsx	UMCDOJ-04373182
D3667			recipe avaialble ratio_0320_CMP.xlsx	UMCDOJ-04373191
D3668			2017 NBD 方針展開 _PM1_Q4_2017_CMP.xlsx	UMCDOJ-04379024
D3669			UMC step naming.xlsx	UMCDOJ-04396324

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3670			2016 OS saving Review and Strategy.pptx	UMCDOJ-04404079
D3671			Strategy template Stephen 0831.pptx	UMCDOJ-04404128
D3672			34條TLR-supporting data.pptx	UMCDOJ-04435071
D3673			34條TLR-supporting data_v2.pptx	UMCDOJ-04435137
D3674			Rule revision 解析.pptx	UMCDOJ-04435617
D3675			5244.lnd	UMCDOJ-05091844
D3676			List of Design rule need support data.pptx	UMCDOJ-05091845
D3677			TLR revision 紀錄_20171124_v5.xlsx	UMCDOJ-05091846
D3678			34條TLR-supporting data_v5.pptx	UMCDOJ-05091847
D3679			47600.lnd	UMCDOJ-05285743
D3680			IT Buildup Strategy V1 - YY.pptx	UMCDOJ-05285744
D3681			1.xlsx	UMCDOJ-05285754
D3682			动态随机存储器研发年度报告 (2016.12).pdf	UMCDOJ-05958612
D3683			03823.msg	UMCDOJ-05970458
D3684			锐仕方达简历报告-蒲莉华-QSM经理 2017.09.21(1).doc	UMCDOJ-05970467
D3685			锐仕方达简历报告-董荆山-质量可靠性/失效分析经理-2017.9.25.doc	UMCDOJ-05970472
D3686			锐仕方达简历报告-邱丁贤-QSM经理 0922.doc	UMCDOJ-05970476
D3687			05722.msg	UMCDOJ-05973885
D3688			智能生產系統部台籍人員招聘-170925.pptx	UMCDOJ-05973887
D3689			郇掄聘隴.jpg	UMCDOJ-05973894
D3690			YikunPeng-Resume_v2.docx	UMCDOJ-05973895
D3691			□□□峇掄踢桶_20170607唵.docx	UMCDOJ-05973901
D3692			鋒緬郇掄□□_□□殍.jpg	UMCDOJ-05973907
D3693			趁居賡畿_□_□□殍_□.pdf	UMCDOJ-05973908
D3694			□□殍薩□桶.pdf	UMCDOJ-05973918

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3695			□□□岢掬踢桶_□掣氮_□□殍.doc	UMCDOJ-05973922
D3696			104-resume-沈佩萱.doc	UMCDOJ-05973926
D3697			Big Data台籍人員招聘-170925.pptx	UMCDOJ-05973930
D3698			2016呬腕謀頰□□.jpg	UMCDOJ-05973935
D3699			Resume-Ting Huan Hsiao.pdf	UMCDOJ-05973936
D3700			A Neural-Network-based Sketch Recognition System .pdf	UMCDOJ-05973937
D3701			□□□岢掬踢桶_隋毆.doc	UMCDOJ-05973941
D3702			系統技術及整合部台籍人員招聘-170925.pptx	UMCDOJ-05973946
D3703			□夢鑿_□.pptx	UMCDOJ-05973955
D3704			□夢鑿薩□.pdf	UMCDOJ-05973960
D3705			劉禾茂簡歷.ppt	UMCDOJ-05973963
D3706			08672.msg	UMCDOJ-05982200
D3707			认识晋华集成电路_20170509-Final.pptx	UMCDOJ-05982202
D3708			09527.msg	UMCDOJ-05984271
D3709			动态随机存储器研发月报 (2017.03).pdf	UMCDOJ-05984272
D3710			3279.msg	UMCDOJ-05999207
D3711			PM1 monthly report_May_2017_v1.pptx	UMCDOJ-05999208
D3712			399.lnd	UMCDOJ-06001765
D3713			在美华人招募.pptx	UMCDOJ-06001767
D3714			Self introduction.pptx	UMCDOJ-06006697
D3715			Sample_english.pptx	UMCDOJ-06006698
D3716			374.lnd	UMCDOJ-06009433
D3717			3411.lnd	UMCDOJ-06105699
D3718			F32 Technology Transfer Proposal Rev2.pptx	UMCDOJ-06105700
D3719			3966.lnd	UMCDOJ-06105887

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3720			F32 Document Transfer Proposal 20180820.pptx	UMCDOJ-06105888
D3721			3984.lnd	UMCDOJ-06105910
D3722			F32 Document Transfer Proposal 20180828.pptx	UMCDOJ-06105911
D3723			3102.lnd	UMCDOJ-06126069
D3724			3230.lnd	UMCDOJ-06261828
D3725			Strategy template Stephen_0725.pptx	UMCDOJ-06261829
D3726			Apple0309_M project introduction_0308r.pptx	UMCDOJ-06522930
D3727			8602.lnd	UMCDOJ-06530681
D3728			M project introduction_0829.pptx	UMCDOJ-06530683
D3729			Basic DRAM operation and Character_20160701.pptx	UMCDOJ-06717541
D3730			04408.lnd	UMCDOJ-06788829
D3731			picture1.gif	UMCDOJ-06788832
D3732			picture2.gif	UMCDOJ-06788833
D3733			picture3.gif	UMCDOJ-06788834
D3734			picture4.gif	UMCDOJ-06788835
D3735			Tech Transfer Native Data Set	UMCDOJTT-00000001
D3736			SC-BC Short Improvement 20180604.pdf	UMCDOJTT-00000192
D3737			AM01 SNPAd W Residue Issue - ET Report.pdf	UMCDOJTT-00000213
D3738			DSA RP_0314-36479-O-5DM-100.pdf	UMCDOJTT-00028770
D3739			ALDSIN BKM migration summary 10032018.pdf	UMCDOJTT-00148191
D3740			Patent - US10103152	N/A
D3741			Patent App. - US20050274102A1	N/A
D3742			Patent App. - US20060131630A1	N/A
D3743			Patent App. - US20060138561A1	N/A
D3744			Patent App. - US20060237766A1	N/A

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3745			Patent App. - US20070134914A1	N/A
D3746			Patent App. - US20080003797A1	N/A
D3747			Patent App. - US20080293212A1	N/A
D3748			Patent App. - US20090026515A1	N/A
D3749			Patent App. - US20090061329A1	N/A
D3750			Patent App. - US20100219467A1	N/A
D3751			Patent App. - US20100270602A1	N/A
D3752			Patent App. - US20110049596A1	N/A
D3753			Patent App. - US20110156262A1	N/A
D3754			Patent App. - US20110263089A1	N/A
D3755			Patent App. - US20120074518A1	N/A
D3756			Patent App. - US20120146221A1	N/A
D3757			Patent App. - US20120211815A1	N/A
D3758			Patent App. - US20120217559A1	N/A
D3759			Patent App. - US20120273876A1	N/A
D3760			Patent App. - US20130075909A1	N/A
D3761			Patent App. - US20130093007A1	N/A
D3762			Patent App. - US20130093093A1	N/A
D3763			Patent App. - US20130168758A1	N/A
D3764			Patent App. - US20130207171A1	N/A
D3765			Patent App. - US20130240959A1	N/A
D3766			Patent App. - US20130288472A1	N/A
D3767			Patent App. - US20130320436A1	N/A
D3768			Patent App. - US20140027924A1	N/A
D3769			Patent App. - US20140061743A1	N/A

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3770			Patent App. - US20140145268A1	N/A
D3771			Patent App. - US20140154882A1	N/A
D3772			Patent App. - US20150014767A1	N/A
D3773			Patent App. - US20150028492A1	N/A
D3774			Patent App. - US20150061004A1	N/A
D3775			Patent App. - US20150061134A1	N/A
D3776			Patent App. - US20150104934A1	N/A
D3777			Patent App. - US20150132936A1	N/A
D3778			Patent App. - US20150171014A1	N/A
D3779			Patent App. - US20150200110A1	N/A
D3780			Patent App. - US20150206806A1	N/A
D3781			Patent App. - US20150214152A1	N/A
D3782			Patent App. - US20150214362A1	N/A
D3783			Patent App. - US20150255464A1	N/A
D3784			Patent App. - US20150294923A1	N/A
D3785			Patent App. - US20150311297A1	N/A
D3786			Patent App. - US20150333069A1	N/A
D3787			Patent App. - US20150349073A1	N/A
D3788			Patent App. - US20160035788A1	N/A
D3789			Patent - US5811869	N/A
D3790			Patent - US6258732	N/A
D3791			Patent - US6406971	N/A
D3792			Patent - US6438052	N/A
D3793			Patent - US7183603	N/A
D3794			Patent - US7276443B2	N/A

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3795			Patent - US7349232	N/A
D3796			Patent - US7410866	N/A
D3797			Patent - US7511328	N/A
D3798			Patent - US7563718	N/A
D3799			Patent - US7736819	N/A
D3800			Patent - US7759248	N/A
D3801			Patent - US7790546	N/A
D3802			Patent - US7915121	N/A
D3803			Patent - US7919385	N/A
D3804			Patent - US8058138	N/A
D3805			Patent - US8225255	N/A
D3806			Patent - US8278201	N/A
D3807			Patent - US8278224	N/A
D3808			Patent - US8283229	N/A
D3809			Patent - US8312394	N/A
D3810			Patent - US8350321	N/A
D3811			Patent - US8405136	N/A
D3812			Patent - US8486801	N/A
D3813			Patent - US8508020	N/A
D3814			Patent - US8524601	N/A
D3815			Patent - US8546218	N/A
D3816			Patent - US8624350	N/A
D3817			Patent - US8652927	N/A
D3818			Patent - US8692371	N/A
D3819			Patent - US8698233	N/A

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3820			Patent - US8729675	N/A
D3821			Patent - US8860110	N/A
D3822			Patent - US8878273	N/A
D3823			Patent - US8896059	N/A
D3824			Patent - US8900967	N/A
D3825			Patent - US9093297	N/A
D3826			Patent - US9136331	N/A
D3827			Patent - US9153579	N/A
D3828			Patent - US9184227	N/A
D3829			Patent - US9202775	N/A
D3830			Patent - US9252205	N/A
D3831			Patent - US9311443	N/A
D3832			Patent - US9589799	N/A
D3833			Patent - US9772555	N/A
D3834			Patent - US9997373	N/A
D3835			GCO wkly update Taiwan Nov 20, 2017.pptx	USD-0667686
D3836			00000000E02DA66FDE743D489FBA4E2A8 1611C1184022000.MSG	USD-0669206
D3837			00000000D775730D1F570D4ABB3D53A3B D0BDA3FA4012000.MSG	USD-0669604
D3838			JHICC Analysis.xlsx	USD-0669605
D3839			JHICC Anaylsis and Proposal Summary to Peter 04132018.pptx	USD-0669606
D3840			02/2016 JHICC Company Overview [English]	USD-0847617
D3841			JHICC Project [English]	USD-0872837
D3842			Email re: Breakdown of 53	[TO COME]
D3843			Schedule of Agreements	[TO COME]
D3844			Email re: Fallback plan	[TO COME]

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3845			Attachment to email re: Fallback plan	[TO COME]
D3846			Email re: 5.1&5.8	[TO COME]
D3847			Email re: 2.6(d) & 9.2	[TO COME]
D3848			Email re: 2.6(d) revision	[TO COME]
D3849			Email re: JH Cash Flow	[TO COME]
D3850			Attachment to email re: JH Cash Flow	[TO COME]
D3851			E-mail re: Draft Technology Cooperation Agreement	[TO COME]
D3852			Attachment to email re: Draft Technology Cooperation Agreement	[TO COME]
D3853			Attachment to email re: Draft Technology Cooperation Agreement	[TO COME]
D3854			E-mail re: DRAM Market Analysis and Strategic Partners	[TO COME]
D3855			Attachment to e-mail re: DRAM Market Analysis and Strategic Partners	[TO COME]
D3856			Email re: Technology Cooperation Agreement	[TO COME]
D3857			Attachment to email re: Technology Cooperation Agreement	[TO COME]
D3858			Technology Development (Cooperation) Contract	[TO COME]
D3859			Minutes of the Fifth Round Meeting of the First Board of Directors Meetings of JHICC	[TO COME]
D3860			Email re: Bod proposals_1117	[TO COME]
D3861			Attachment to email re: Bod proposals_1117	[TO COME]
D3862			Statement of F32 DRAM Manufacturing Equipment List	[TO COME]
D3863			Independent Technology R&D Progress Report	[TO COME]
D3864			Employment Contract re: Chen Zhengkun	[TO COME]
D3865			Letter of Appointment re: Chen Zhengkun	[TO COME]
D3866			Resolution of Board of Directors of JHICC	[TO COME]
D3867			PPT of Matters of Photomask Revision Purchase	[TO COME]
D3868			Resolutions of the Ninth Round Meeting of the First Board of Directors Meetings of	[TO COME]
D3869			Resolutions of the Tenth Round Meeting of the First Board of Directors Meetings of	[TO COME]

EXHIBIT NUMBER	MARKED	ADMITTED	DESCRIPTION OF EXHIBIT	BATES
D3870			2017 R&D Team Bonuses Distribution Plan Presentation	[TO COME]
D3871			E-mail re: Document transferred to JHICC (DRAM F32 Design Rule)	[TO COME]
D3872			Memorandum on Procurement of Special R&D Tools	[TO COME]
D3873			E-mail re: DRAM Development Annual Report of Y2017	[TO COME]
D3874			Attachment to email re: DRAM Development Annual Report of Y2017	[TO COME]
D3875			Attachment to email re: Draft Technology Cooperation Agreement	[TO COME]
D3876			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3877			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3878			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3879			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3880			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3881			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3882			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3883			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3884			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3885			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3886			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3887			Attachment to email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3888			Email re: Transfer materials for SINO SEMIC Visiting	[TO COME]
D3889			UMC/JHICC DRAM Process Technology Co-Development Outline	[TO COME]
D3890			Note on the Change of the President's Salary Payment to Full Amount	[TO COME]